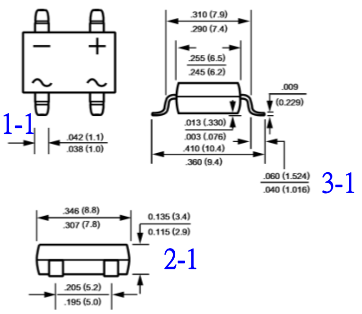
RECTRON SEMICONDUCTOR

Final Product/Material Change Notification
Document #: DB-S
Issue Date: 2020/4/9
PCN#: 2020040701DBS

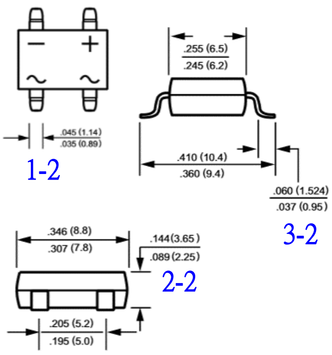
Title of Change:	**DB-S** package size change.
Proposed first ship date	**August 1st, 2020 (90 days)**
Contact information:	Please contact Rectron Semiconductor Sales Office or visit www.rectron.com for nearest contact information.
Samples:	Please contact Rectron Semiconductor Sales Office or visit www.rectron.com for nearest contact information. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Please contact Rectron Semiconductor Sales Office or visit www.rectron.com for nearest contact information.
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. Rectron Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, please visit www.rectron.com for nearest contact information
Change Part Identification:	**Datasheet revision change per below**
Change Category:	☐ Material ■Machine/Tooling ☐Method ☐Manufacture site ☐Man
Change Sub-Category(s):	☐Manufacturing Site Transfer ☐Material Change ■Datasheet/Product Doc change ☐Manufacturing Process Change ☐Product specific change ☐Shipping/Packaging/Marking ☐ Manufacturing Site Addition ☐Other:
Last order date for previous version	
Description and Purpose:	About **DB-S** package , old molding tools phased out, new molding tools phase in .

Point:	Change
1.Pin width	**Old max 1.1mm, min 1.0mm** **new max 1.14mm, min 0.89mm**
2.Body height	**Old max 3.4mm, min 2.9mm** **new max 3.65mm, min 2.25mm**
3.Length of pin solder PCB board	**Old** **max 1.524mm, min 1.016mm** **new** **max 1.524mm, min 0.95mm**

Before change Description



After change Description



Reliability Data Summary:			
QV DEVICE NAME:		**DB-S**	
Hi-real test	**Sample size(PC)**	**Condition**	**ACC/REJ**
High Temperature Reverse Bias	77	Ta=150℃±5℃ VR=480V. for 1000 Hrs.	ACC
Thermal Fatigue Testing	77	ON : 300 sec / Off : 300 sec for 1000 cycles	ACC
Solder resistance	77	260±5℃ for 10±2 Sec.	ACC
Thermal Shock	77	55℃±5℃/5MIN AND 150±5℃/5MIN for 100 cycles	ACC
Electrical Characteristic Summary:		Electrical characteristics are not impacted	
List of Affected Parts:		Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the PCN Customized Portal.	
Part Number	**New spec version**	**Addition**	**Mark**
DB101S DB102S DB103S DB104S DB105S DB106S DB107S	**DB101S~DB107S** **202004-97-E**	**Including to House #**	
DB1012S	**DB1012S-DB1014S** **202004-97-B**	**Including to House #**	
DB1014S	**DB1012S-DB1014S** **202004-97-B**	**Including to House #**	
LDB101S-LDB107S	**LDB101S ~ LDB107S** **202004-97-B**	**Including to House #**	
DB151S-DB1512S	**DB151S~DB1512S** **202004-97-D**	**Including to House #**	
DB2014S	**DB2014S** **202004-97-B**	**Including to House #**	
DB201S-DB207S	**DB201S - DB207S** **202004-97C**	**Including to House #**	
EDB101S ~ EDB107S	**EDB101S~EDB107S** **202004-97-E**	**Including to House #**	
KDB3200S	**KDB3200S** **202004-97-A**	**Including to House #**	
DB159LS	**DB159LS** **202004-97-A**	**Including to House #**	
HDB101lS-HDB108lS	**HDB101LS~ HDB108LS** **202004-97-A**	**Including to House #**	